



January 2015

# FDMS7678

## N-Channel Power Trench<sup>®</sup> MOSFET 30 V, 26 A, 5.5 mΩ

### Features

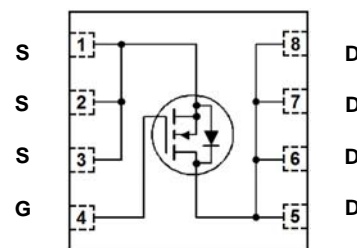
- Max  $r_{DS(on)}$  = 5.5 mΩ at  $V_{GS}$  = 10 V,  $I_D$  = 17.5 A
- Max  $r_{DS(on)}$  = 6.8 mΩ at  $V_{GS}$  = 4.5 V,  $I_D$  = 15 A
- High performance technology for extremely low  $r_{DS(on)}$
- Termination is Lead-free
- RoHS Compliant

### General Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced Power Trench<sup>®</sup> process that has been especially tailored to minimize the on-state resistance. This device is well suited for Power Management and load switching applications common in Notebook Computers and Portable Battery Packs.

### Applications

- DC - DC Buck Converters
- Notebook battery power management
- Load switch in Notebook



### MOSFET Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Ratings	Units
$V_{DS}$	Drain to Source Voltage	30	V
$V_{DSI}$	Drain to Source Transient Voltage ( $t_{\text{Transient}} < 100$ ns)	33	V
$V_{GS}$	Gate to Source Voltage (Note 3)	$\pm 20$	V
$I_D$	Drain Current -Continuous (Package limited) $T_C = 25^\circ\text{C}$	26	A
	Drain Current -Continuous (Silicon limited) $T_C = 25^\circ\text{C}$	72	
	-Continuous $T_A = 25^\circ\text{C}$ (Note 1a)	17.5	
	-Pulsed	70	
$E_{AS}$	Single Pulse Avalanche Energy (Note 4)	54	mJ
$P_D$	Power Dissipation $T_C = 25^\circ\text{C}$	41	W
	Power Dissipation $T_A = 25^\circ\text{C}$ (Note 1a)	2.3	
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ\text{C}$

### Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	3	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	50	

### Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMS7678	FDMS7678	Power 56	13 "	12 mm	3000 units

**Electrical Characteristics**  $T_J = 25\text{ }^{\circ}\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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**Off Characteristics**

$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = 250\text{ }\mu\text{A}$ , $V_{GS} = 0\text{ V}$	30			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$ , referenced to $25\text{ }^{\circ}\text{C}$		21		mV/ $^{\circ}\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 24\text{ V}$ , $V_{GS} = 0\text{ V}$			1	$\mu\text{A}$
$I_{GSS}$	Gate to Source Leakage Current, Forward	$V_{GS} = 20\text{ V}$ , $V_{DS} = 0\text{ V}$			100	nA

**On Characteristics**

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}$ , $I_D = 250\text{ }\mu\text{A}$	1.2	1.5	3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$ , referenced to $25\text{ }^{\circ}\text{C}$		-5		mV/ $^{\circ}\text{C}$
$r_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10\text{ V}$ , $I_D = 17.5\text{ A}$		4.7	5.5	m $\Omega$
		$V_{GS} = 4.5\text{ V}$ , $I_D = 15\text{ A}$		5.6	6.8	
		$V_{GS} = 10\text{ V}$ , $I_D = 17.5\text{ A}$ , $T_J = 125\text{ }^{\circ}\text{C}$		6.3	7.4	
$g_{FS}$	Forward Transconductance	$V_{DD} = 5\text{ V}$ , $I_D = 17.5\text{ A}$		90		S

**Dynamic Characteristics**

$C_{iss}$	Input Capacitance	$V_{DS} = 15\text{ V}$ , $V_{GS} = 0\text{ V}$ $f = 1\text{ MHz}$		1810	2410	pF
$C_{oss}$	Output Capacitance			620	820	pF
$C_{rss}$	Reverse Transfer Capacitance			75	110	pF
$R_g$	Gate Resistance		0.1	0.7	2.5	$\Omega$

**Switching Characteristics**

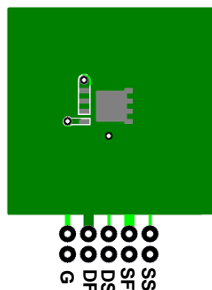
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 15\text{ V}$ , $I_D = 17.5\text{ A}$ $V_{GS} = 10\text{ V}$ , $R_{GEN} = 6\text{ }\Omega$		10	19	ns
$t_r$	Rise Time			4	10	ns
$t_{d(off)}$	Turn-Off Delay Time			26	41	ns
$t_f$	Fall Time			3	10	ns
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0\text{ V to }10\text{ V}$	$V_{DD} = 15\text{ V}$ $I_D = 17.5\text{ A}$	28	39	nC
	Total Gate Charge	$V_{GS} = 0\text{ V to }4.5\text{ V}$		14	19	nC
$Q_{gs}$	Gate to Source Charge			4.4		nC
$Q_{gd}$	Gate to Drain "Miller" Charge			3.9		nC

**Drain-Source Diode Characteristics**

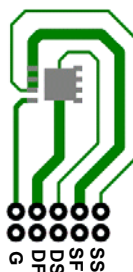
$V_{SD}$	Source to Drain Diode Forward Voltage	$V_{GS} = 0\text{ V}$ , $I_S = 1.9\text{ A}$ (Note 2)		0.7	1.2	V
		$V_{GS} = 0\text{ V}$ , $I_S = 17.5\text{ A}$ (Note 2)		0.8	1.2	
$t_{rr}$	Reverse Recovery Time	$I_F = 17.5\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$		30	49	ns
$Q_{rr}$	Reverse Recovery Charge			13	23	nC

## NOTES:

1.  $R_{\theta JA}$  is determined with the device mounted on a 1 in<sup>2</sup> pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta CA}$  is determined by the user's board design.



a. 50  $^{\circ}\text{C}/\text{W}$  when mounted on a 1 in<sup>2</sup> pad of 2 oz copper



b. 125  $^{\circ}\text{C}/\text{W}$  when mounted on a minimum pad of 2 oz copper

2. Pulse Test: Pulse Width < 300  $\mu\text{s}$ , Duty cycle < 2.0 %.

3. As an N-ch device, the negative  $V_{GS}$  rating is for low duty cycle pulse occurrence only. No continuous rating is implied.

4.  $E_{AS}$  of 54 mJ is based on starting  $T_J = 25\text{ }^{\circ}\text{C}$ ,  $L = 0.3\text{ mH}$ ,  $I_{AS} = 19\text{ A}$ ,  $V_{DD} = 27\text{ V}$ ,  $V_{GS} = 10\text{ V}$ .

# Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

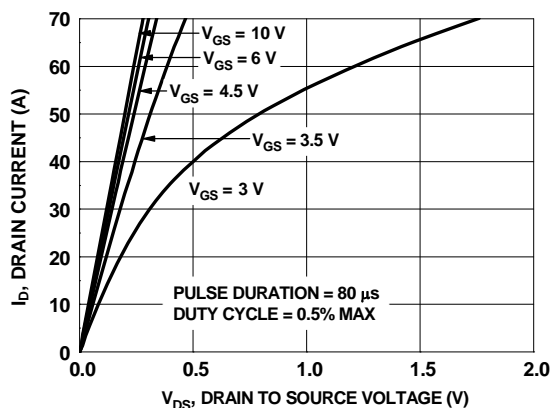


Figure 1. On Region Characteristics

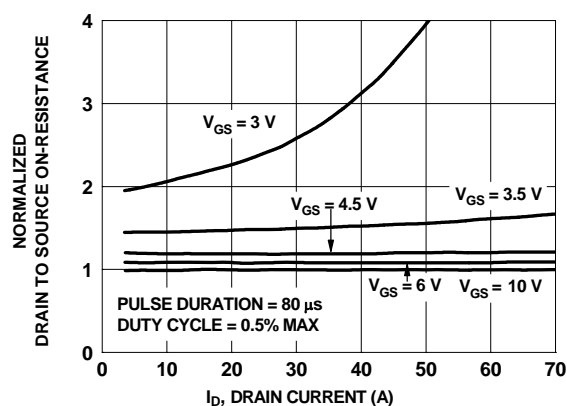


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

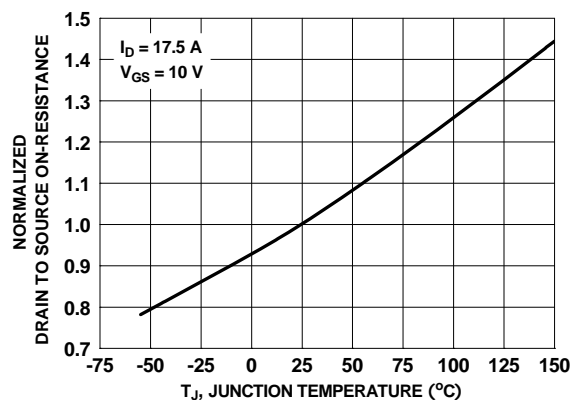


Figure 3. Normalized On Resistance vs Junction Temperature

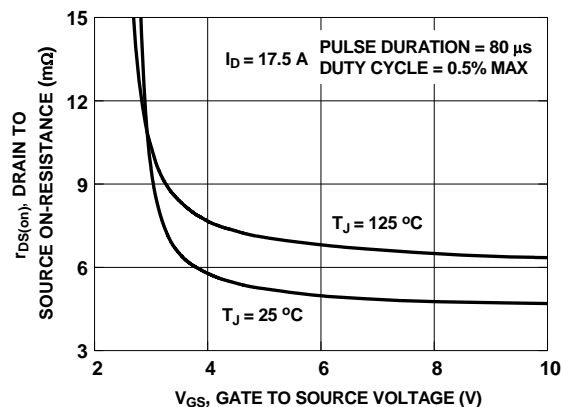


Figure 4. On-Resistance vs Gate to Source Voltage

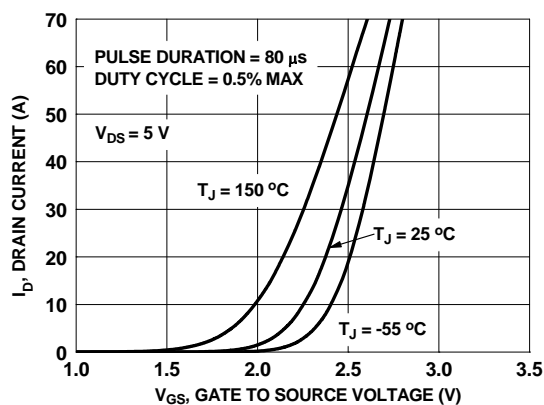


Figure 5. Transfer Characteristics

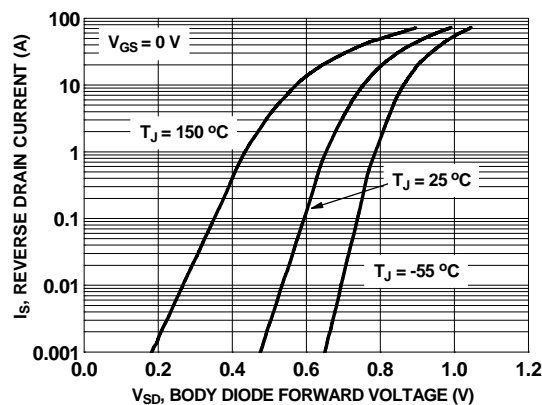


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

# Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

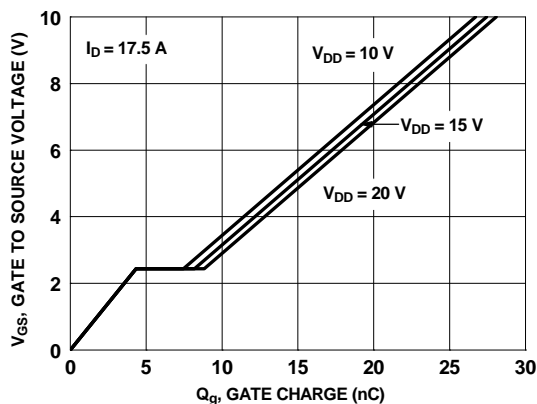


Figure 7. Gate Charge Characteristics

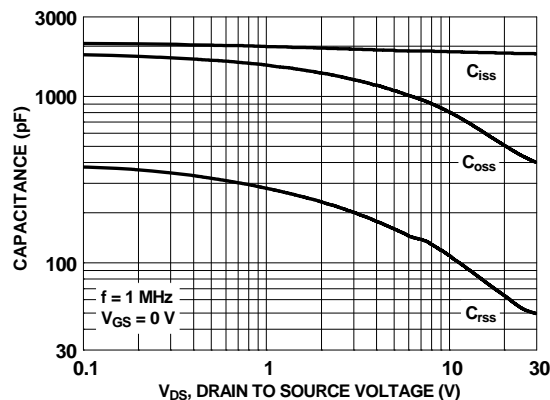


Figure 8. Capacitance vs Drain to Source Voltage

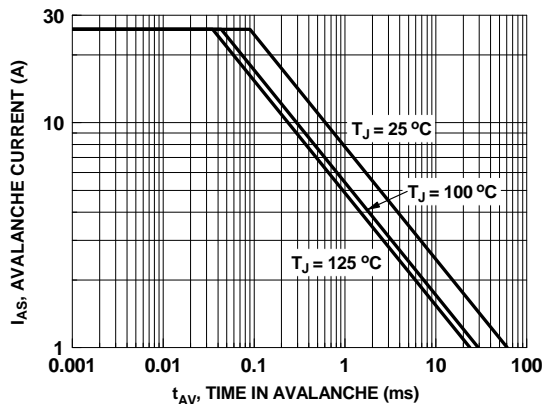


Figure 9. Unclamped Inductive Switching Capability

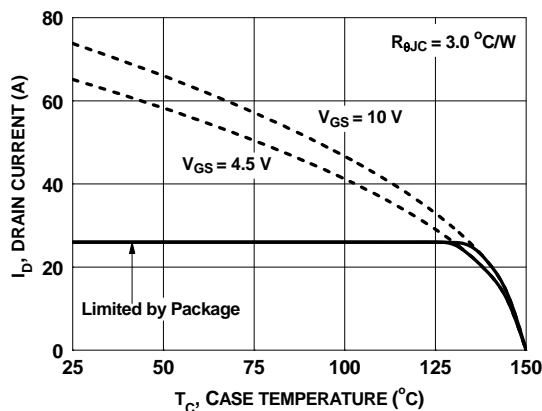


Figure 10. Maximum Continuous Drain Current vs Case Temperature

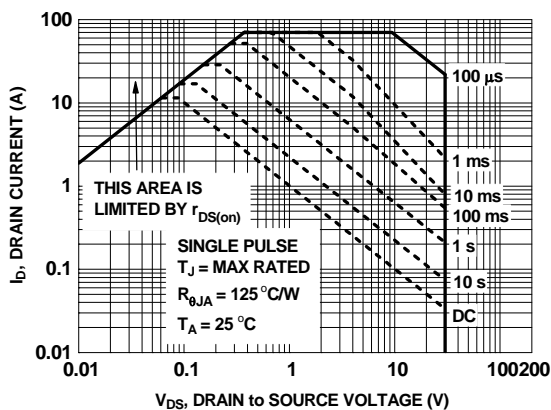


Figure 11. Forward Bias Safe Operating Area

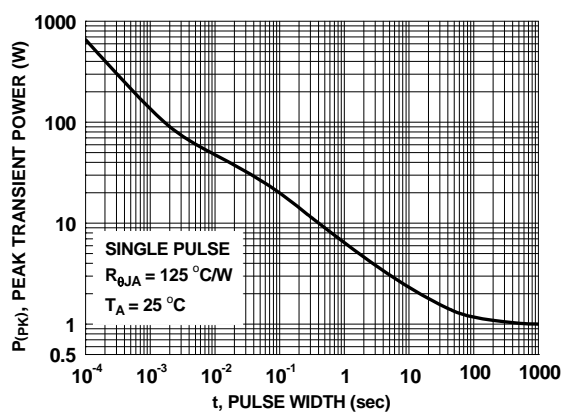


Figure 12. Single Pulse Maximum Power Dissipation

# Typical Characteristics $T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise noted

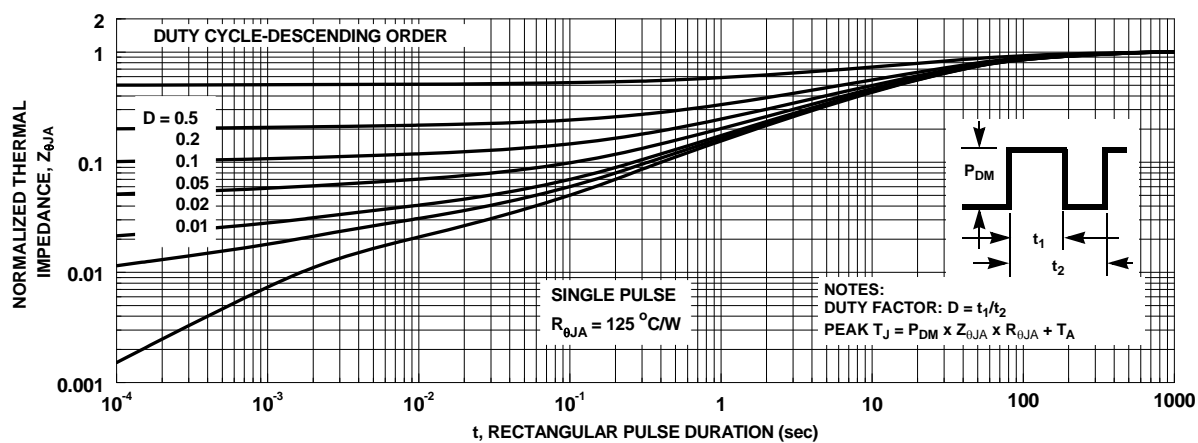
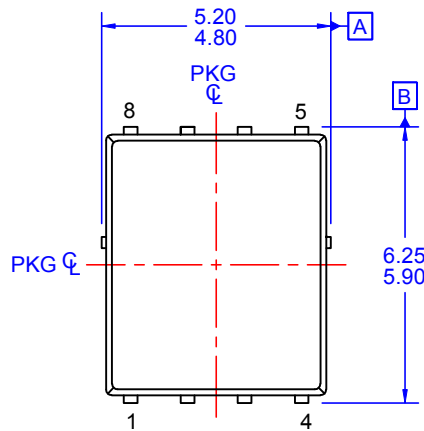
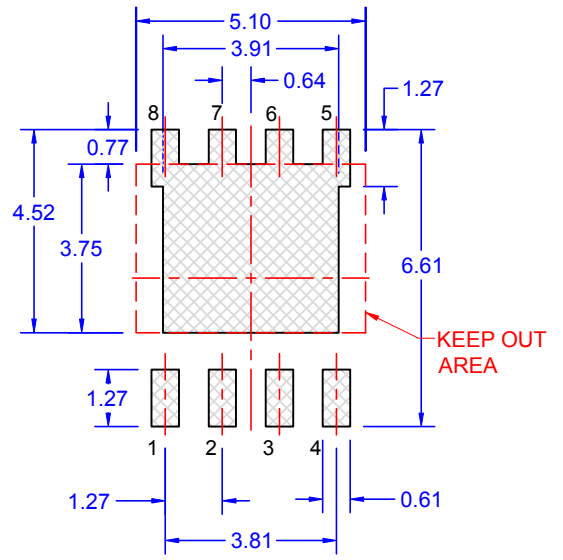
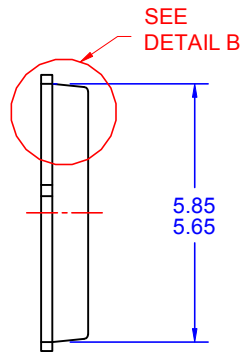


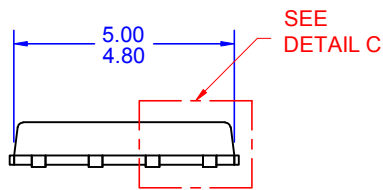
Figure 13. Junction-to-Ambient Transient Thermal Response Curve



TOP VIEW

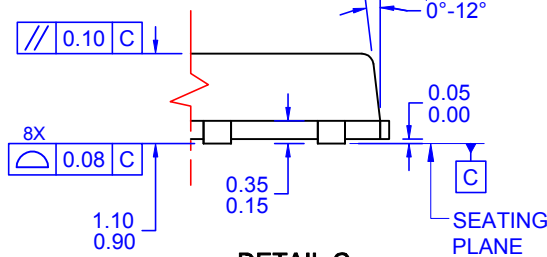


LAND PATTERN  
RECOMMENDATION



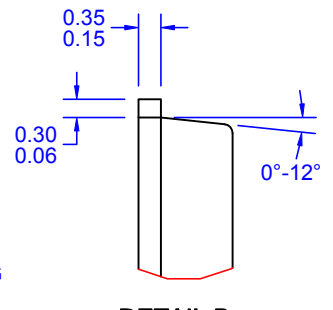
SIDE VIEW

OPTIONAL DRAFT  
ANGLE MAY APPEAR  
ON FOUR SIDES  
OF THE PACKAGE



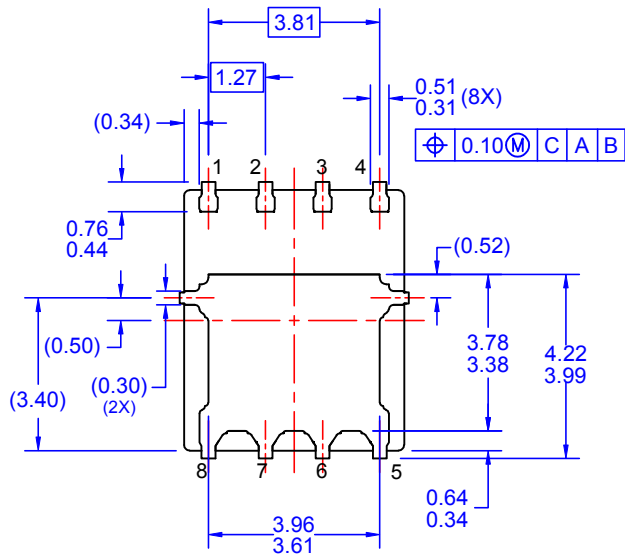
**DETAIL C**

SCALE: 2:1



**DETAIL B**

SCALE: 2:1



BOTTOM VIEW

NOTES: UNLESS OTHERWISE SPECIFIED

- PACKAGE STANDARD REFERENCE: JEDEC MO-240, ISSUE A, VAR. AA, DATED OCTOBER 2002.
- DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- ALL DIMENSIONS ARE IN MILLIMETERS.
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- IT IS RECOMMENDED TO HAVE NO TRACES OR VIAS WITHIN THE KEEP OUT AREA.
- DRAWING FILE NAME: PQFN08AREV8





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FAST®	MVN®	Sync-Lock™	Xsens™
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No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
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